

Listing Of Claims

Claims 1-43 (canceled)

Claims 44-53 (withdrawn)

Claims 54-73 (canceled)

Claims 74-76 (withdrawn)

77. (currently amended) A method for testing a semiconductor wafer ~~having a plurality of contact locations~~ comprising:

providing a testing apparatus ~~comprising in electrical communication with~~ a test circuitry configured to apply test signals to the wafer, a suspended plate, a substrate on the suspended plate, and a force applying mechanism comprising a plurality of electrical connectors in contact with the suspended plate in electrical communication with the test circuitry;

~~providing a mounting plate on the testing apparatus comprising a plurality of pads and a plurality of conductors in electrical communication with the pads;~~

~~providing a substrate on the mounting plate comprising a plurality of contact members in electrical communication with the conductors configured to electrically contact the contact locations on the wafer;~~

~~providing a plurality of spring loaded electrical connectors on the testing apparatus in electrical communication with the test circuitry and in physical and electrical contact with the pads on the mounting plate;~~

biasing the substrate against the wafer using the suspended plate and the force applying mechanism; and
~~a biasing force applied by the electrical connectors; and~~

applying the test signals through the electrical connectors, through the suspended plate and through the substrate to the wafer.

~~contact members to the contact locations.~~

78. (currently amended) The method of claim 77 wherein a membrane mounts the suspended plate on the testing apparatus.

~~the pads are arranged in a grid array.~~

79. (currently amended) The method of claim 77 further comprising providing a compressible member between the suspended plate and the substrate.

~~wherein the electrical connectors comprise pogo pins.~~

80. (currently amended) The method of claim 77 wherein the substrate includes a plurality of contact members configured to electrically contact a plurality of contact locations on the wafer.

~~each contact member comprises a raised member comprising a surface and a projection on the surface configured to penetrate a contact location on the wafer.~~

81. (currently amended) The method of claim ~~77~~ 80 wherein each contact member comprises an indentation in the substrate or a projection on the substrate.

~~at least partially covered by a conductive layer.~~

82. (previously presented) The method of claim 77 wherein the testing apparatus comprises a wafer prober.

Claims 83-90 (withdrawn)

91. (new) In a test system including a testing apparatus for a semiconductor wafer, a method for testing the wafer comprising:

suspending a substrate on the testing apparatus;
providing a force applying mechanism on the testing apparatus comprising a plurality of electrical connectors configured to bias the substrate against the wafer;
biasing the substrate against the wafer using the force applying mechanism; and
applying test signals through the electrical connectors and the substrate to the wafer.

92. (new) The method of claim 91 wherein the suspending step is performed by connecting a membrane to a plate attached to the substrate.

93. (new) The method of claim 92 wherein each electrical connector comprises a pin.

94. (new) The method of claim 93 wherein the substrate comprises a plurality of contact members configured to electrically engage contact locations on the wafer.

95. (new) The method of claim 94 wherein the contact locations comprise bumps and the contact members comprise indentations and conductive layers on the indentations.

96. (new) The method of claim 94 wherein the contact locations comprise pads and the contact members comprise projections configured to penetrate the pads.